

CLAIMS

What is claimed is:

1. An under bump metallization structure applicable to be disposed on bonding pads of a semiconductor wafer, wherein a passivation layer covers the wafer and exposes the bonding pads, the under bump metallization structure comprising:

an adhesive layer formed on the bonding pads;

a first barrier layer disposed on the adhesive layer;

a wetting layer formed on the first barrier layer; and

a second barrier layer disposed on the wetting layer, wherein a material of the second barrier comprises tin and copper.
2. The structure of claim 1, wherein the quantity of the tin is smaller than the quantity of the copper.
3. The structure of claim 1, wherein the first barrier layer is a nickel-vanadium layer.
4. The structure of claim 1, wherein the wetting layer is a copper layer.
5. The structure of claim 1, wherein the wetting layer is a nickel layer.
6. The structure of claim 1, wherein the wetting layer is a titanium layer.
7. The structure of claim 1, wherein the thickness of the second barrier layer is ranged from about 50 μm to about 80 μm .
8. A semiconductor wafer applicable to a flip chip device, comprising:

an active surface;

a plurality of bonding pads formed on the active surface;

a passivation covering the active surface and exposing the bonding pads;

a first electrically conductive layer formed on the bonding pads; and

a second electrically conductive layer formed on the first electrically conductive layer, wherein the second electrically conductive layer is a tin-copper layer.

9. The semiconductor wafer of claim 8, further comprising a plurality of bumps formed above the bonding pads and attached to the second electrically conductive layer.
10. The semiconductor wafer of claim 8, wherein the second electrically conductive layer is extended above the active surface.
11. The semiconductor wafer of claim 8, further comprising a dielectric layer covering the second electrically conductive layer and exposing a portion of the second electrically conductive layer to form a redistributed pad.
12. The semiconductor wafer of claim 11, further comprising a bump formed on the redistributed pad.
13. The semiconductor wafer of claim 8, wherein a material of the first electrically conductive layer is selected from the group of aluminum, titanium, titanium-vanadium alloy, titanium-tungsten alloy, copper, nickel-copper alloy, and nickel, nickel-vanadium alloy.
14. The semiconductor wafer of claim 8, wherein the first electrically conductive layer comprises a titanium layer, an aluminum layer, a nickel-vanadium alloy layer and a copper layer and the titanium layer is directly attached to the bonding pads.

15. The semiconductor wafer of claim 8, wherein a material of the dielectric layer comprises polyimide.
16. The semiconductor wafer of claim 8, wherein the quantity of the tin is smaller than the quantity of the copper.
17. The semiconductor wafer of claim 8, wherein the thickness of the lead-alloy layer is at least larger than 50 μ m.
18. The semiconductor wafer of claim 8, wherein a material of the dielectric layer comprises Benzocyclobutene.
19. The semiconductor wafer of claim 8, wherein the dielectric layer is a polymer layer.